Optical Chiplet / Co-Packaged Optics

-Under development -

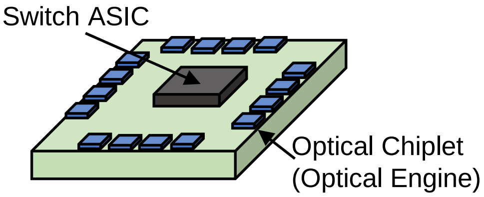
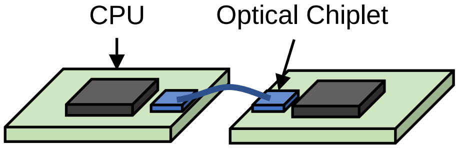
Features

- Small, Optical Chiplet* assembly with highly efficient connection between optical devices and Fiber Array
- Co-Packaged Optics (CPO) assembly with Optical Chiplet, and optical communication between xPU (CPU, GPU, etc.) packages

*Optical Chiplet : An optoelectronic device that integrates a photonic integrated circuit (PIC) and an electronic integrated circuit (EIC) used in high-density packaging technology.

Technologies

- For optoelectronic convergence, SHINKO is developing optical assembly and optical wiring technologies in addition to our core technologies in semiconductor package substrates and IC assembly.

<table>
<tr><th></th><th>Board to Package</th><th>Package to Package</th></tr>
<tr><td rowspan="2">Use Case</td><td colspan="2">On Semiconductor Package</td></tr>
<tr><td>Network Switch</td><td>Server</td></tr>
<tr><td>Structure</td><td> </td><td> </td></tr>
<tr><td>Core Technologies</td><td colspan="2">◆Assembly ◆Active Alignment ◆Thin and High-density Wiring Substrate</td></tr>
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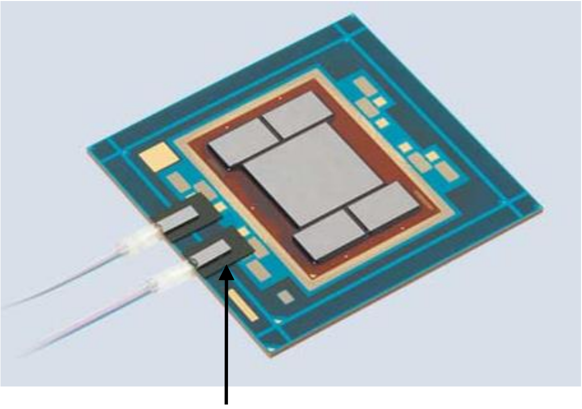
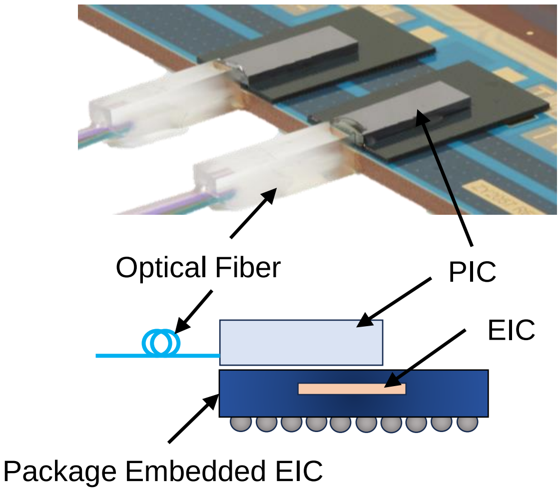
Structure

- Optical interface (photoelectric conversion device) placed at the edge of the semiconductor package





Optical Chiplet Structure

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